CBC testing status

CMS Binary Chip 130nm CMOS chip for short strip readout at sLHC

chips under test since 14th February

early test results presented ACES workshop - March 10th

summary of testing status presented CMS Upgrade workshop ~ 2 weeks ago

will repeat those results again here

but add some more "work-in-progress" type measurements

Tracker week electronics meeting, May 2011. Mark Raymond, Imperial College.

CBC introduction

2.5 -> 1.25 DC-DC converter

key features

- designed for short strips, \sim 2.5–5cm, < \sim 10 pF
- full size prototype 128 channels (50 μm pitch)
- not contributing to L1 trigger (could be adapted to 2-in-1 type triggering)
- binary un-sparsified readout chip & system simplicity, low power
- powering test features
 2.5 -> 1.2 DC-DC converter
 LDO regulator (1.2 -> 1.1) feeds analog FE

main functional blocks

- fast front end amplifier 20 nsec peaking
- comparator with programmable threshold trim
- 256 deep pipeline (6.4 us)
- 32 deep buffer for triggered events
- output shift register and SLVS driver
- fast (SLVS) and slow (I2C) control interfaces

some target specs

- DC coupling to sensor up to 1 uA leakage
- · can be used for both sensor polarities
- noise: < 1000e for C_{SENSOR} ~5 pF
- power consumption
 - < 0.5 mW/channel for $\rm C_{SENSOR} \sim 5 \ pF$



CBC front end



preamp

resistive feedback absorbs I_{leak} T network for holes Rf.Cf implements short diff. time constant (good for no pile-up)

postamp

provides gain and int. time constant ~ 50 mV / fC AC coupled removes I_{leak} DC shift individually programmable O/P DC level implements channel threshold tuning 8-bits, 0.8 mV / bit, 200 mV range

comparator

global threshold (indiv. tuning at postamp O/P) programmable hysteresis



basic functionality

communication interfaces

- fast: SLVS (Scalable Low Voltage Signalling) SLVS circuits provided by CERN (S. Bonacini, K.Kloukinas) used for 40 MHz clock I/P, L1 trig and data out
- **slow:** I2C used to programme bias generator operational modes, latency,.. 128 comparator threshold trim values

output data frame

following trigger get 12-bit header

2 start bits, 2 error bits (latency, fifo overflow), 8 bit pipe address followed by 128 channel bits



50 nsec / division

e.g. 2 consecutive data frames (2 triggers) st header 2nd header fC signal niected on one channel volts 0.0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0 4.5 μsec



leakage current tolerance

200k

60k

92k

¹115k

Ileak absorbed by preamp resistive feeback

=> DC shift at preamp O/P

electrons mode

single 200k resistor, leakage shifts output +ve

plenty of headroom

holes mode

T network produces +ve offset leakage shifts output -ve

sufficient headroom for 1 uA

(note: waveforms include ~ 300 mV offset due to source follower on test channel O/P)



testing front end performance using comparator

can learn a lot about front end performance by varying: comparator threshold magnitude of injected charge

can look at S-curves no. of events vs. threshold value fit with complementary error function (erfc) gives mean signal (S-curve midpoint) and sigma

=> gain and noise



S-curves and gain



noise

plots show dependence on external added capacitance in both operational polarities

current in input transistor adjusted to maintain pulse shape - so overall analogue power varies

results very close to simulation (open circles)

target spec. < 1000e for 5 pF sensor



external capacitance [pF]



"hit detect" circuit

hit detect circuit sits between comparator output and pipeline

operates in 2 modes:

- *variable* raw comp. O/P sampled into pipeline consecutive pipeline samples high as long as comp. O/P stays high
- *single* comp. O/P shortened to single 25ns pulse only one sample in pipeline however long comp. O/P stays high



hit detect functionality

sweep signal charge injection time for both modes of operation – fixed trigger time

comparator threshold fixed at 1 fC

VARIABLE mode picture shows pulse width increasing as signal amplitude increases

SINGLE mode picture shows *hit* detect circuit keeps pulse width at 25 ns

timewalk ~ 15 ns (just within spec.)



explanation of charge injection pictures (1)



2 signals : big signal in red, small signal in black

raw comparator output stays high as long as postamp O/P exceeds threshold

picture above shows both signals injected at same time

will now "walk through" scenario where charge injection time varied w.r.t. pipeline sampling clock

explanation of charge injection pictures (2)



inject 2 signals : big signal in red, small signal in black

always triggering same pipeline column (hit detect circuit in variable mode)

"trigger time" = clock edge which writes comp O/P into the triggered pipeline column

T1 : earliest time of **big signal** charge injection for comparator output to be registered at trigger time

T2 : earliest time of small signal charge injection for comparator output to be registered at trigger time

in terms of charge injection delay, **T1 < T2**

explanation of charge injection pictures (3)





some time later...

T3 : latest time of small signal charge injection for comparator output to be registered at trigger time

T1 < T2 < T3

explanation of charge injection pictures (4)





... later still

T4 : **latest** time of **big signal** charge injection for comparator output to be registered at trigger time

T1 < **T2** < **T3** < **T4**

time-walk pictures vs. external capacitance



- VARIABLE MODE

SINGLE MODE -

increasing noise "rounds off" the edges

start to lose efficiency for 1.25 fC signals at larger capacitances



comparator threshold uniformity

all channels have same comparator global threshold (VCTH)

individual channel tuning achieved by introducing programmable offset on the comparator input signal (postamp O/P)

128 registers, 8-bit precision

peak-to-peak threshold spread ~ 30 mV

< 1 fC before tuning

pictures demonstrate effectiveness of tuning to achieve comp. threshold matching

~ mV precision achievable

threshold tuning - 16 channels



comparator threshold uniformity (2)

correlation between S-curve midpoints before tuning and offset register values after

- can maybe use to get first approximation to overall uniformity
- but individual scans required to achieve final close matching

=> a lot of I2C activity





CBC biasing - currents

can choose to bias CBC using internal reference 64 uA derived from bandgap

or provide external current (via resistor)

plot shows current biases measured using both methods external tuned to 64 uA => internal reference very close to 64uA (at least for this chip)





VCTH problem



VCTH drive circuit can source current but sink capability fixed at 25 uA if VCTH > Postamp output for all channels, then Nint positive for all channels

500k in parallel for all channels = $\sim 4k$

~ 0.5 V / 4k = 125 uA

drive circuit can't sink this so VCTH gets pulled high

- can fix with external resistor to ground (on VCTH pad) to provide extra current

or drive VCTH with external DAC

(look for better fix for next CBC version)



VCTH vs I2C setting





power circuitry

CBC incorporates on-chip circuitry to investigate powering options

switched cap. DC-DC (CERN) converts 2.5 -> 1.25 in scenario where buck converter provides 2.5 V from 12 V rail

can use 1.25 to provide CBC digital supply

LDO regulator

regulates 1.25 -> 1.1 for analogue front end uses CERN bandgap for voltage reference







LDO included to provide clean, regulated rail to analog FE

~ 1.2 Vin, 1.1 Vout

uses CERN bandgap as Vref (0.6 V)

bandgap output (BGO) and input to LDO (BGI) taken to pads to allow to measure and/or over-ride

LDO design needs care to achieve stability no stability issues found with CBC design

LDO - DC performance

DC measurements show LDO performing well

bandgap flat down to 0.9 V

dropout only 30 mV for 60 mA load

load regulation

~ 5 mV change in Vout for 60 mA change in load







LDO - AC performance



measurement techniques still under development - work in progress

in principle simple

superimpose sinusoidal waveform on DC supply (LDO I/P) measure what appears on LDO O/P

in practice

difficult to introduce and measure signals "clean" measurement complicated by stray components (e.g. track parasitics)

design issue identified

bandgap output affected by noise on supply - passes it on to LDO can fix with external capacitor on BGO/BGI - need better fix in future

measuring LDO - AC performance



probably need to improve technique to exclude parasitic effects as much as possible

maybe need a dedicated test setup?

LDO - AC performance

LDO O/P measured for 100 mV p-p sinewave ripple on 1.25 V DC LDO I/P

PSRR = 20.log[(LDO O/P)/(LDO I/P)]

measurement has some agreement with simulation

with bandgap decoupled get v.good rejection at low frequencies (signals at limit of measurability)

discrepancies at highest frequencies (> ~ 20-30 MHz)

but quite good rejection up to ~ 10 MHz





DC-DC circuit measurements

DCDC switched capacitor converts 2.5 -> \sim 1.2 using 1 MHz clock

measure voltages using differential probe between signal under study and nearest ground area

yellow stars show probe points on CBC test board



DC-DC circuit results

red/blue waveforms either end of wire link on CBC test board

should be the same voltage

differences possibly due to

differences in local parasitic impedances? probe pick-up?

efficiency measured for ~ nominal CBC load 2.52 V / 14.2 mA -> 1.2 V / 26.4 mA => ~ 90%

effect of DC-DC circuit on CBC channel noise under study





power consumption

analogue depends on sensor capacitance 130 + (21 x C_{SENSOR}[pF]) uW

digital

 $I_{VDDD} = 2.8 - 4.5$ mA for whole chip (depending on SLVS bias setting)

< 50 μ W / channel

no measurable dependence on L1 trigger rate (0 - 100 kHz) digital circuitry functions correctly down to $V_{DDD} = 0.9V$

total

180 + (21 x C_{SENSOR}[pF]) uW

e.g. < 300 uW for 5 pF sensor capacitance

(c.f. APV25 ~2.7 mW / chan. (but long strips))





testing programme status

baseline performance (conventional (clean) powering scheme)

digital functionality

fast (Ck/T1 - SLVS) & slow control (I2C) interfaces setup and operation

analogue functionality

amplifier

pulse shape, noise, linearity, overload tolerance, ...

 $C_{\mbox{\scriptsize IN}}$ dependence, signal polarity dependence, across chip & chip-to-chip uniformity leakage current tolerance

comparator

timewalk, threshold tuning and uniformity, hysteresis

all above will depend on bias generator settings => large parameter space to cover

power consumption

powering options studies

supply sensitivity with/without various on-chip options

longer term

temperature effects (~ all of above vs. T) tests with sensors radiation: ionizing & SEU sensitivity test beam hope to put simple setup in beam later in the year

blue = reasonably advanced
green = needs more work
red = not looked at yet

single CBC + sensor test board



transition board and interface board could be connected by twisted pair flat cable

nothing tested yet

future directions

currently looking at:

1) bump-bonded version

allows to integrate pitch adaption to sensor on hybrid hybrid has to be "hi-tech" substrate fine pitch bonding (C4 ~ 250 μm) and tracking chip layout should proceed in parallel with substrate design things to learn about hybrid technology and impact on chip plenty of scope for collaboration here





2) 256 channel version with 2-in-1 triggering capability

existing CBC L1 triggered short strip chip can be adapted to provide 2-in-1 type trigger data for CMS outer tracker

need

cluster width discrimination offset and correlation trigger formation and transmission

summary

130 nm CBC prototype working quite well

already providing valuable information performance achievable and power budget required

no show-stopping problems

mainly biasing issues - relatively simple workarounds will not stop us learning all we need to from this prototype

long testing programme ahead, including

powering options - further studies temperature effects tests with sensors radiation: ionizing & SEU sensitivity test beam

CBC documentation:

http://icva.hep.ph.ic.ac.uk/~dmray/CBC_documentation/